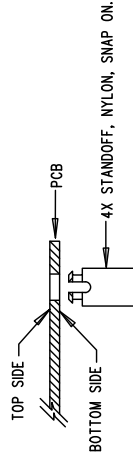





1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPENDLIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		 <div>830 MCARDY BLVD MILPITAS, CA 95035 PH: (408) 432-1800 www.linear.com FOR CUSTOMER USE ONLY</div>		TITLE: TOP ASSEMBLY DRAWING		REV.	
PCB DES.	Hz	Mike S.		HIGH CURRENT STEP-DOWN CONVERTER WITH VID PROGRAMMING AND LOW DCR INDUCTORS		1	
APP ENG.				SIZE		REV.	
				IC NO.		REV.	
				N/A		REV.	
SCALE = NONE				LTC3877EUK		REV.	
				DEMO CIRCUIT 2229A		REV.	
				SHT 1 OF 2		REV.	
				FILENAME: DC2229A-2.PCB		REV.	